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FOR IMMEDIATE RELEASE

Press Release

An ECTC Special Presentation by Dr. Wusheng Yin
An Overview of Advanced Materials

(**Albany, NY**) **May 7, 2015** We at YINCAE Advanced Materials, LLC would like to cordially invite you to a special presentation, *An Overview of Advanced Materials* by Dr. Wusheng Yin; our President. YINCAE develops and manufactures a wide range of materials including:

- Solder Joint Encapsulants
- Underfill Materials
- Die Attach Adhesives
- Conformal Coatings
- Nano Composite Formulations
- Wafer Level Materials
- Optoelectronic Material
- Thermal Interface Material

YINCAE offers a variety Adhesives, Thermal Interface, and Chip/ Board/ Packaging level materials for any level of necessity. Dr. Yin created the WORLD's FIRST Lead -Free **S**older **J**oint **E**ncapsulation **A**dhesive solutions for wafer level, flip chip, POP, LGA, BGA and many more. YINCAE offers SJEA for low, medium, and high temperature solder alloy applications with differential chemistry and electrical/ thermal conductivity for your individualized needs.

Date: Wednesday, May 27 2015
Time: 1:00pm-3:00 pm
Location: Sheraton Hotel (4th Floor- Rooms 411/415) on-site of the ECTC 2015 Conference.

For more information or if you have any questions please feel free to contact the Administrative Office: www.yincae.com or 518-452-2880. We look forward to seeing you there.